

November 2013

FDB38N30U N-Channel UniFETTM Ultra FRFETTM MOSFET 300 V, 38 A, 120 m Ω

Features

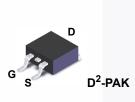
- $R_{DS(on)}$ = 120 m Ω (Max.) @ V_{GS} = 10 V, I_D = 19 A
- Low Gate Charge (Typ. 56 nC)
- Low C_{rss} (Typ. 55 pF)
- 100% Avalanche Tested
- RoHS Compliant

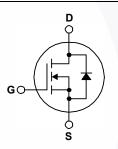
Applications

- Uninterruptible Power Supply
- LCD/LED/PDP TV
- AC-DC Power Supply

Description

UniFETTM MOSFET is Fairchild Semiconductor's high voltage MOSFET family based on planar stripe and DMOS technology. This MOSFET is tailored to reduce on-state resistance, and to provide better switching performance and higher avalanche energy strength. UniFET Ultra FRFETTM MOSFET has much superior body diode reverse recovery performance. Its trr is less than 50nsec and the reverse dv/dt immunity is 20V/nsec while normal planar MOSFETs have over 200nsec and 4.5V/nsec respectively. Therefore UniFET Ultra FRFET MOSFET can remove additional component and improve system reliability in certain applications that require performance improvement of the MOSFET's body diode. This device family is suitable for switching power converter applications such as power factor correction (PFC), flat panel display (FPD) TV power, ATX and electronic lamp ballasts.





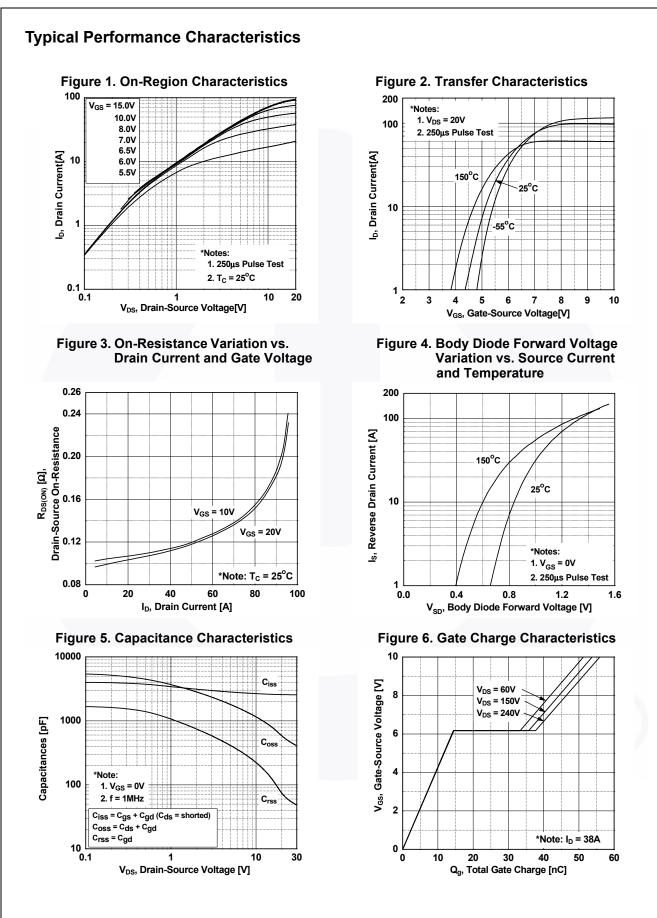
MOSFET Maximum Ratings T_C = 25°C unless otherwise noted.

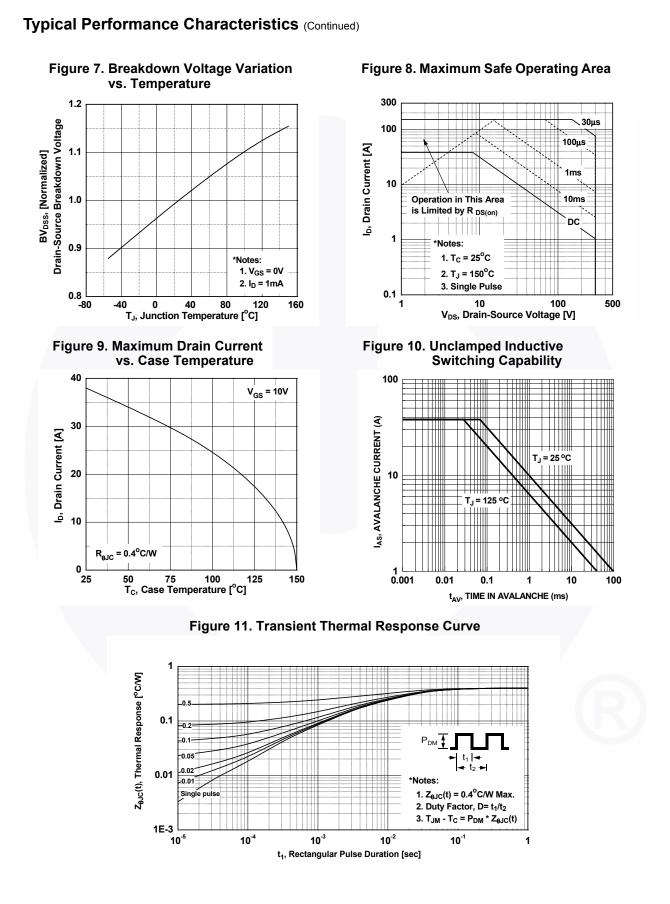
Symbol	Parameter		FDB38N30U	Unit	
V _{DSS}	Drain to Source Voltage		300	V	
V _{GSS}	Gate to Source Voltage			±30	V
ID	DrainCurrent	- Continuous (T _C = 25 ^o C)		38	A
		- Continuous (T _C = 100 ^o C)		22.8	
I _{DM}	Drain Current	- Pulsed	(Note 1)	152	А
E _{AS}	Single Pulsed Avalanche Energy (Note 2)		722	mJ	
I _{AR}	Avalanche Current		(Note 1)	38	А
E _{AR}	Repetitive Avalanche Ene	rgy	(Note 1)	31.3	mJ
dv/dt	Peak Diode Recovery dv/	dt	(Note 3)	20	V/ns
P _D	Power Dissipation	(T _C = 25 ^o C)		313	W
		- Derate Above 25°C		2.5	W/ ^o C
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C	
TL	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds		Seconds	300	°C

Thermal Characteristics

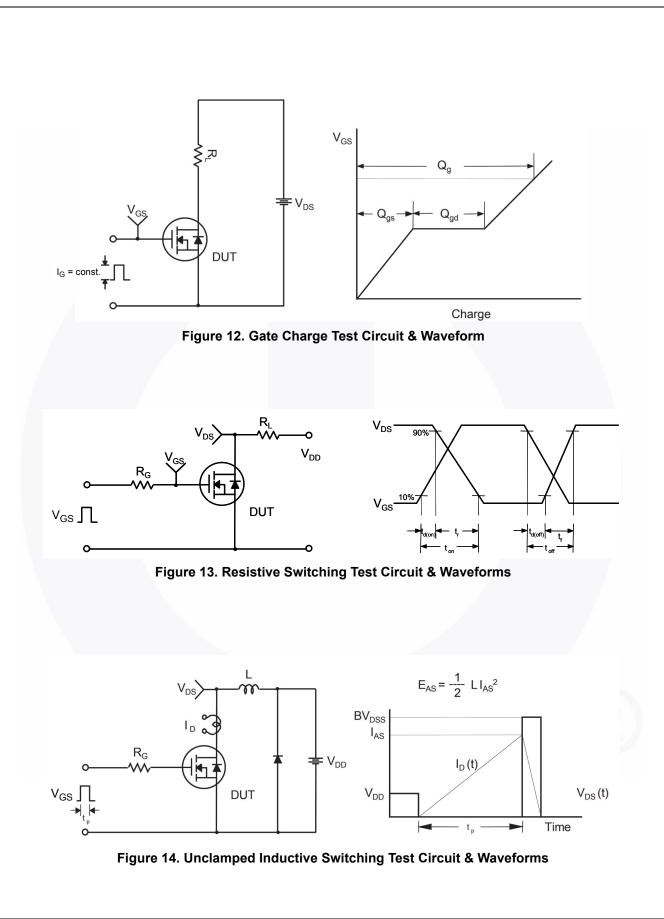
Symbol	Parameter	FDB38N30U	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	0.4	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	62.5	0/00

Cteristics T _C = 25°C ur Parameter ource Breakdown Voltage n Voltage Temperature t voltage Drain Current ody Leakage Current eshold Voltage in to Source On Resistance	I _D = I _D = V _{DS} V _{DS}	wise noted. Test Conditions 250 μ A, V _{GS} = 0 V, T, 250 μ A, Referenced t = 300 V, V _{GS} = 0 V = 240 V, T _C = 125°C = ±30 V, V _{DS} = 0 V	_J = 25 ^o C	Min. 300 - -	Typ . - 0.33 - -	Max.	Uni V V/°(
ource Breakdown Voltage n Voltage Temperature t e Voltage Drain Current ody Leakage Current eshold Voltage	I _D = V _{DS} V _{DS}	250 μA, V _{GS} = 0 V, T, 250 μA, Referenced t = 300 V, V _{GS} = 0 V = 240 V, T _C = 125 ^o C	_J = 25 ^o C	300 - - -	- 0.33 -	- - 25	V V/º(
n Voltage Temperature t voltage Drain Current ody Leakage Current shold Voltage	I _D = V _{DS} V _{DS}	250 μA, Referenced t = 300 V, $V_{GS} = 0 V$ = 240 V, $T_C = 125^{\circ}C$		-	0.33	- 25	V/º(
n Voltage Temperature t voltage Drain Current ody Leakage Current shold Voltage	I _D = V _{DS} V _{DS}	250 μA, Referenced t = 300 V, $V_{GS} = 0 V$ = 240 V, $T_C = 125^{\circ}C$		-	0.33	- 25	V/º(
t voltage Drain Current ody Leakage Current eshold Voltage	I _D = V _{DS} V _{DS}	250 μA, Referenced t = 300 V, $V_{GS} = 0 V$ = 240 V, $T_C = 125^{\circ}C$		-	-	25	
e Voltage Drain Current ody Leakage Current eshold Voltage	V _{DS} V _{DS}	= 300 V, V _{GS} = 0 V = 240 V, T _C = 125°C		-	-	25	
ody Leakage Current	V _{DS}	= 240 V, $T_C = 125^{\circ}C$		-	-		
eshold Voltage					-		μΑ
eshold Voltage	VGS	$= \pm 30$ V, V _{DS} = 0 V				250	
				-	-	±100	nA
in to Source On Resistance	V _{GS}	= V _{DS} , I _D = 250 μA		3.0	-	5.0	V
in to obuice on Resistance	V _{GS}	= 10 V, I _D = 19 A		-	0.103	0.120	Ω
ransconductance	V _{DS}	= 20 V, I _D = 19 A		-	30	-	S
istics							
					2510	2240	~F
	V _{DS} = 25 V, V _{GS} = 0 V,		-				pF pF
	f = 1	l MHz	-				pF
	V	V = 240 V I = 20 A		-	56	73	nC
-			-		14	-	nC
	00		(Note 4)	-	24	-	nC
	1		1		1		
,	V	- 150 \/ - 28 A		-			ns
				-			ns
,	• 65			-			ns
			(Note 4)	-	02	134	ns
Characteristics							
Continuous Drain to Source	Diode Forv	ward Current		-	-	38	A
Pulsed Drain to Source Diod	le Forward	Current		-	-	152	A
ource Diode Forward Voltage	e V _{GS}	= 0 V, I _{SD} = 38 A		-	-	1.4	V
Recovery Time		$V_{GS} = 0 V, I_{SD} = 38 A,$ $dI_F/dt = 100 A/\mu s$		-	60		ns
lecovery Charge	dl _F /d			-	0.097	· ·	μΟ
	Pulsed Drain to Source Diod	acitance VDS apacitance f = 1 iransfer Capacitance f = 1 acitance f = 1 balance f = 1 acitance f = 1 balance f = 1 acitance f = 1 balance f =	acitance $V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ apacitance $F = 1 \text{ MHz}$ Transfer Capacitance $V_{DS} = 240 \text{ V}, I_D = 38 \text{ A}$ acitance Gate Charge $V_{DS} = 240 \text{ V}, I_D = 38 \text{ A}$ acitance Gate Charge $V_{GS} = 10 \text{ V}$ arain "Miller" Charge $V_{DD} = 150 \text{ V}, I_D = 38 \text{ A},$ acitance Gate Charge $V_{DD} = 150 \text{ V}, I_D = 38 \text{ A},$ acitance Gate Charge $V_{DD} = 150 \text{ V}, I_D = 38 \text{ A},$ acitance Gate Charge $V_{DD} = 10 \text{ V}, R_G = 25 \Omega$ acitance Gate Characteristics $V_{GS} = 10 \text{ V}, R_G = 25 \Omega$ acitance Continuous Drain to Source Diode Forward CurrentPulsed Drain to Source Diode Forward Currentpulsed Drain to Source Diode Forward Currentaccovery Time $V_{GS} = 0 \text{ V}, I_{SD} = 38 \text{ A},$	acitance $V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1 MHzTransfer Capacitancef = 1 MHzCharge at 10V $V_{DS} = 240 \text{ V}, I_D = 38 \text{ A}$ $V_{GS} = 10 \text{ V}$ Delay Time $V_{DS} = 10 \text{ V}, I_D = 38 \text{ A},$ $V_{GS} = 10 \text{ V}$ Delay Time $V_{DD} = 150 \text{ V}, I_D = 38 \text{ A},$ $V_{GS} = 10 \text{ V},$ $R_G = 25 \Omega$ Delay Time $V_{DD} = 150 \text{ V}, R_G = 25 \Omega$ Delay Time $(Note 4)$ Delay Time $(Note 4)$ Delay Time $V_{DS} = 10 \text{ V}, R_G = 25 \Omega$ Delay Time $(Note 4)$ Delay Time $(Note 4)$ Delay Time $(Note 4)$ Delay Time $V_{CS} = 0 \text{ V}, I_SD = 38 \text{ A},$ Delay Time $V_{CS} = 0 \text{ V}, I_{SD} = 38 \text{ A},$ Delay Time $V_{GS} = 0 \text{ V}, I_{SD} = 38 \text{ A},$ Delay Time $V_{GS} = 0 \text{ V}, I_{SD} = 38 \text{ A},$ Delay Time $V_{GS} = 0 \text{ V}, I_{SD} = 38 \text{ A},$ Delay Time $V_{GS} = 0 \text{ V}, I_{SD} = 38 \text{ A},$	acitance apacitance $V_{DS} = 25 \text{ V}, \text{ V}_{GS} = 0 \text{ V},$ f = 1 MHz-Transfer Capacitancef = 1 MHz-e Charge at 10V $V_{DS} = 240 \text{ V}, \text{ I}_D = 38 \text{ A}$ $V_{GS} = 10 \text{ V}$ -pource Gate Charge rain "Miller" Charge $V_{GS} = 10 \text{ V}$ -reisticsDelay Time rain Time $V_{DD} = 150 \text{ V}, \text{ I}_D = 38 \text{ A},$ $V_{GS} = 10 \text{ V}, \text{ R}_G = 25 \Omega$ -call TimeV_{DD} = 150 \text{ V}, \text{ R}_G = 25 \Omega-call Time(Note 4)-call Time(Note 4)-continuous Drain to Source Diode Forward Current-Pulsed Drain to Source Diode Forward Current-pource Diode Forward Voltage $V_{GS} = 0 \text{ V}, \text{ I}_{SD} = 38 \text{ A},$ vecovery Time $V_{GS} = 0 \text{ V}, \text{ I}_{SD} = 38 \text{ A},$ -	acitance apacitance $V_{DS} = 25 \text{ V}, \text{ V}_{GS} = 0 \text{ V},$ f = 1 MHz-2510Transfer Capacitance e Charge at 10V $V_{DS} = 25 \text{ V}, \text{ V}_{GS} = 0 \text{ V},$ f = 1 MHz-470Ource Gate Charge rain "Miller" Charge $V_{DS} = 240 \text{ V}, \text{ I}_D = 38 \text{ A},$ $V_{GS} = 10 \text{ V}$ -56Delay Time Rise TimeV_{DD} = 150 \text{ V}, \text{ I}_D = 38 \text{ A}, $V_{GS} = 10 \text{ V}$ -24Delay Time call TimeV_{DD} = 150 \text{ V}, \text{ I}_D = 38 \text{ A}, $V_{GS} = 10 \text{ V}, \text{ R}_G = 25 \Omega$ -33Output call Time-62Continuous Drain to Source Diode Forward CurrentPulsed Drain to Source Diode Forward Sub Sub Sub Su	acitance $V_{DS} = 25 \text{ V}, \text{ V}_{GS} = 0 \text{ V},$ - 2510 3340 apacitance f = 1 MHz - 470 625 acransfer Capacitance f = 1 MHz - 55 85 a Charge at 10V VDS = 240 V, ID = 38 A - 56 73 purce Gate Charge VGS = 10 V - 14 - rain "Miller" Charge VGS = 10 V - 24 - ource Gate Charge VGS = 10 V - 24 - rain "Miller" Charge VDD = 150 V, ID = 38 A, - 80 170 belay Time VGS = 10 V, RG = 25 \Omega - 133 276 all Time VGS = 10 V, RG = 25 \Omega - 62 134 e Characteristics - 62 134 e Characteristics - - 38 Pulsed Drain to Source Diode Forward Current - - 152 ource Diode Forward Voltage VGS = 0 V, ISD = 38 A, - - 1.4 Recovery Time

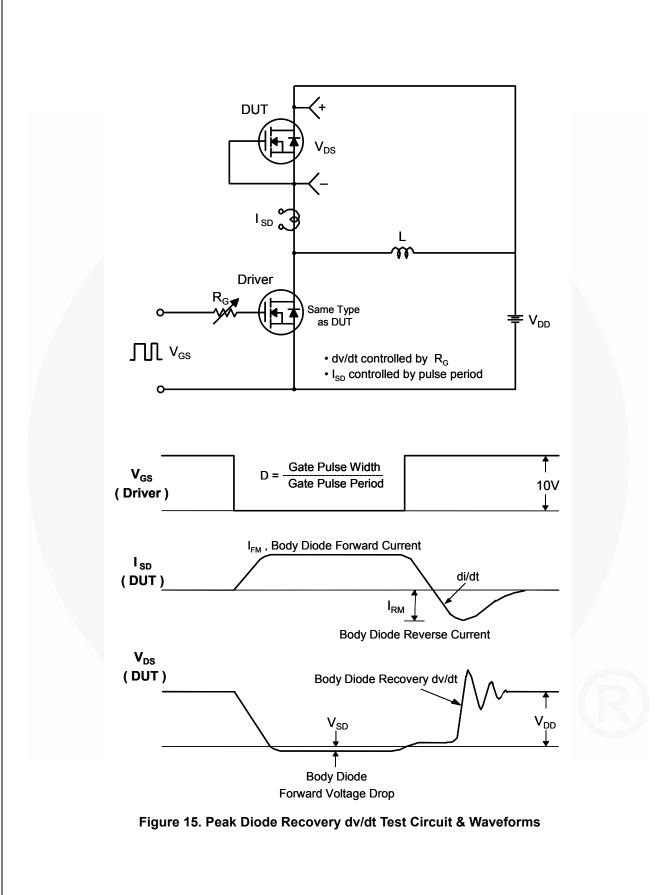


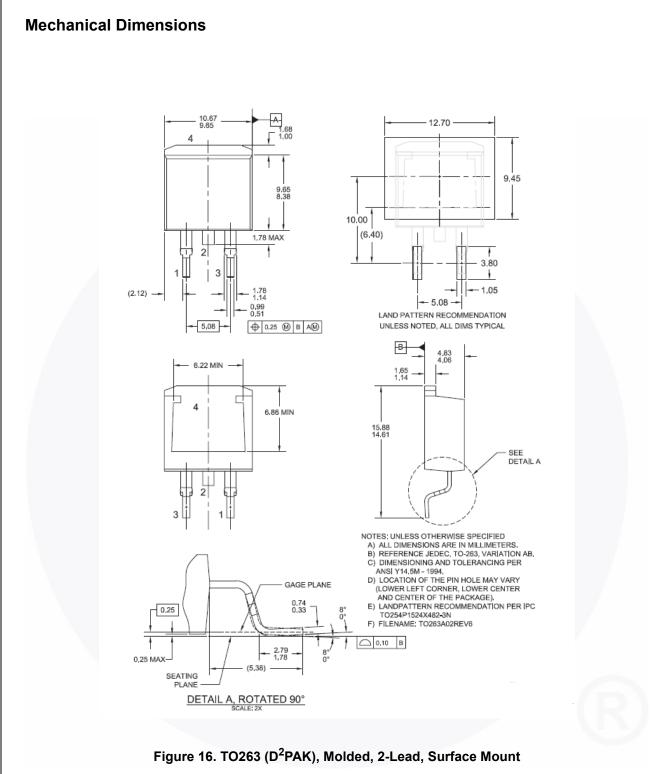


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